



RE965-02PIN

- Adapter DPAK3 with pins
- Epoxy fibre-glass 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Hot air leveling (HAL leadfree)
- Solder stop mask
- Adaption circuit board for DPAK3 with 4.70 mm pitch
- With pin header
- Hole spacing 2.54 mm
- Hole diameter 1.10 mm with solder pads Ø 2.10 mm
- Shield pad & cooling field
- Size 13,50 x 21,50 mm